PATENT



In re Application of:

Connell et al.

Serial No.: 10/706,212

Filed: November 12, 2003

For: WAFER BACK SIDE COATING TO BALANCE STRESS FROM PASSIVATION LAYER ON FRONT OF WAFER AND BE USED AS A DIE ATTACH ADHESIVE

Confirmation No.: 6326

Examiner: G. Eckert II

Group Art Unit: 2815

Attorney Docket No.: 2269-5083.1US

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

March 17, 2005

Date

Leta M. Howard Name (Type/Print)

SUPPLEMENTAL AMENDMENT

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450

Sir:

Prior to examination of the above-referenced patent application on the merits, entry of the amendments as set forth herein is respectfully solicited.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing which begins on page 8 of this paper.

Remarks begin on page 12 of this paper.